16-Channel Constant Current Driver

Product Description

The SCT2016 is a sixteen channels constant current driver best for the LED lighting. It provides the finest PWM control effect by sinking constant current from LED clusters with minimum pulse width 80nS. The PWM control is performed by connecting the PWM signal from system control unit to OE pin of SCT2016. The full scale current value of each output is set by an external resistor connected to REXT pin.

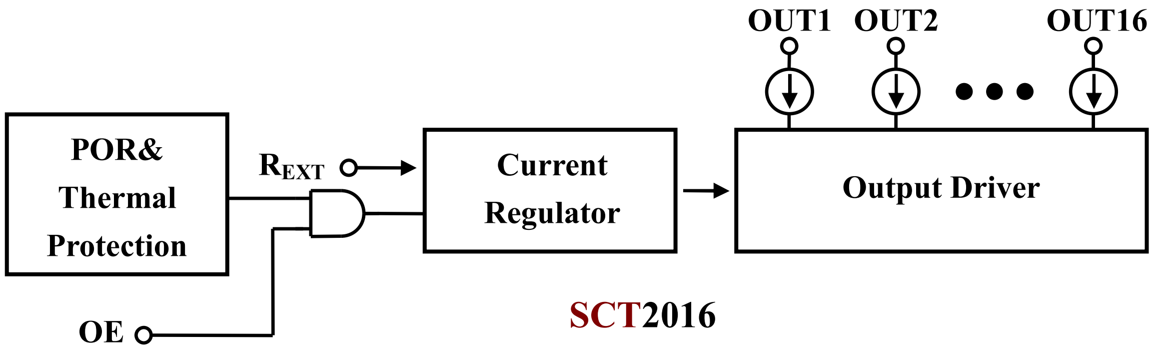
The SCT2016 guarantees to endure maximum DC 24V at each output port. Each output of SCT2016 can sink a constant current up to 80mA. Users can simply shunt the outputs to get higher current driver-ability, especially in the case of high power LED lighting.

The excellent current regulation capability allows SCT2016 easily drive each output current to a constant stable status nearly without affecting by power supply of LED, loading due to variant V_F of LEDs and operating temperature. The SCT2016 is equipped with over temperature protection. The sixteen channels IC stops driving the output while sense its junction temperature exceeds the 180°C high limit and the output will be reactivated while the junction temperature is below the 130°C low limit. In conclusion, the driver system is protected from damage of overheat.

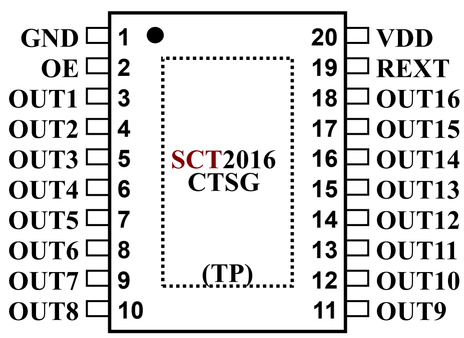
Features

- Sixteen constant-current outputs rate at 24V
- Current regulated output channels, constant current range: 5 – 80mA
- Constant current source invariant to load voltage change
- Fast output current control, the minimum output enable pulse width = 80ns
- ±2%(typ) current matching between outputs
- ±4%(typ) current matching between ICs
- Low dropout output 0.4V@20mA
- All output current are adjusted through one external resistor
- Dimming control available
- Built-in power on reset and thermal protection function
- Supply voltage range: 5V
- Package: TSSOP20
- Application: LED lighting, LED backlight, LED lamp

Block Diagram



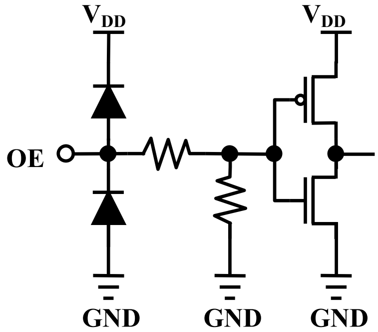
Pin Configuration



Terminal Description

Pin No.	Pin Name	Function
1	GND	Ground terminal
2	OE	Input terminal of output enable signal. Output is enabled when OE is high.
3~18	OUT1~16	Output terminals with constant current
19	REXT	Input terminal connected to an external resistor for setting up all output current
20	VDD	Supply voltage terminal
-	TP	NC, connecting thermal pad to ground is suggested

Equivalent Circuits of Inputs



Ordering information

Part	Marking	Package	Unit per reel(pcs)
SCT2016CTSG	SCT2016CTSG	Green TSSOP20 with thermal pad	2500

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Maximum Ratings (T_A = 25°C)

Characteristic		Symbol	Rating	Unit
Supply voltage		V_{DD}	7	V
Input voltage		V_{IN}	-0.2 ~ V_{DD}+0.2	V
Output current		I_{OUT}	90	mA/Channel
Output voltage		V_{OUT}	24	V
Total GND terminals current		I_{GND}	1200	mA
Power dissipation(Free Air)	TSSOP20	P_D	1.39	W
Thermal resistance(Free Air)	TSSOP20	$R_{TH(j-a)}$	90	°C /W
Operating temperature		T_{OPR}	-40~+85	°C
Storage temperature		T_{STG}	-55~+150	°C

The absolute maximum ratings are a set of ratings not to be exceeded. Stresses beyond those listed under "Maximum Ratings" may cause the device breakdown, deterioration even permanent damage. Exposure to the maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions (T_A=-40 to 85°C unless otherwise noted)

Characteristic	Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply voltage	V_{DD}	-	4.5	-	5.5	V
Output voltage	V_{OUT}	Output OFF	-	-	24	V
		Output ON	-	1	4	V
Output current	I_{OUT}	DC test circuit	5	-	80	mA
Input voltage	V_{IH}	-	2	-	V_{DD}	V
	V_{IL}	-	0	-	0.4	V
OE pulse width	t_w	V_{DD}=4.5~5.5V	80	-	-	ns

Electrical Characteristics (V_{DD}=5V, T_A=25°C unless otherwise noted)

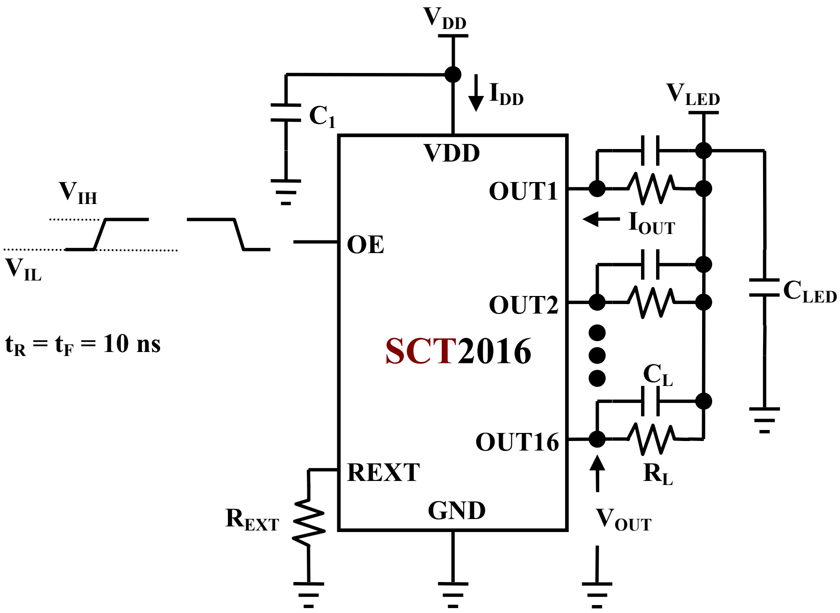
Characteristic		Symbol	Conditions		Min.	Typ.	Max.	Unit
Input voltage		V_{IH}	-		2	-	V_{DD}	V
		V_{IL}	-		0	-	0.4	V
Output leakage current		I_{OL}	V_{OUT} = 24V		-	-	0.5	uA
Output current		I_{OUT}	V_{OUT}=1V	R_{EXT}=900Ω	-	21	-	mA
Current channel skew[1]		dI_{OUT1}	V_{OUT}=1V	R_{EXT}=900Ω	-	±2	±3	%
Current chip skew[2]		dI_{OUT2}	V_{OUT}=1V	R_{EXT}=900Ω	-	±4	±6	%
Line regulation[3] I_{OUT} vs. V_{DD}		$\%/dV_{DD}$	4.5V < V_{DD} < 5.5V V_{OUT} > 1V		-	-	±1	%/V
Load regulation[4] I_{OUT} vs. V_{OUT}		$\%/dV_{OUT}$	1V < V_{OUT} < 4V R_{EXT}=900Ω, V_{DD} = 5V		-	-	±1	%/V
Pull-down resistor		R_{DOWN}	OE		-	500	-	KΩ
Thermal shutdown		T_H	Junction Temperature		-	180	-	°C
		T_L			-	130	-	°C
Supply current	OFF	$I_{DD(OFF)1}$	R_{EXT} = Open, V_{DD} = 5V OUT_1~OUT_{16}=OFF		-	6	15	mA
		$I_{DD(OFF)2}$	R_{EXT} = 900Ω, V_{DD} = 5V OUT_1~OUT_{16}=ON		-	9	15	
	ON	$I_{DD(ON)}$	R_{EXT} = 900Ω, V_{DD} = 5V OUT_1~OUT_{16}=ON		-	10	15	

1. Bit skew=(I_{OUT}-I_{AVG})/I_{AVG}, where I_{AVG}=($I_{OUT(max)}$+ $I_{OUT(min)}$)/2
2. Chip skew=(I_{AVG}-I_{CEN})/I_{CEN}*100(%), where I_{CEN} is the statistics distribution center of output currents.
3. Line regulation=[I_{OUT}(V_{DD}=5.5V)-I_{OUT}(V_{DD}=4.5V)]/(5.5V-4.5V)*100(%/V)
4. Load regulation=[I_{OUT}(V_{OUT}=4V)-I_{OUT}(V_{OUT}=1V)]/(4V-1V)*100(%/V)

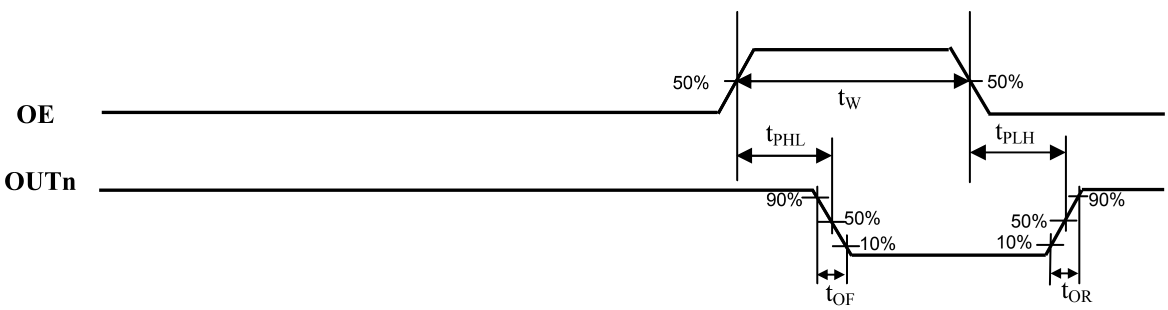
Switching Characteristics (V_{DD}=5V, T_A=25°C unless otherwise noted)

Characteristic		Symbol	Conditions	Min.	Typ.	Max.	Unit
Propagation delay time ("L" to "H")	OE - OUTn	t_{PLH}	V_{DD} = 5 V V_{LED} = 5V V_{IH} = V_{DD} V_{IL}= GND R_{EXT} = 900Ω R_L = 180Ω C_L = 10pF C_1 = 1uF C_{LED} = 100uF	-	50	100	ns
Propagation delay time ("H" to "L")	OE - OUTn	t_{PHL}		-	30	60	ns
Pulse width	OE	t_w		80	-	-	ns
Output rise time of I_{OUT}		t_{OR}		-	10	25	ns
Output fall time of I_{OUT}		t_{OF}		-	10	25	ns

Test Circuit for Switching Characteristics

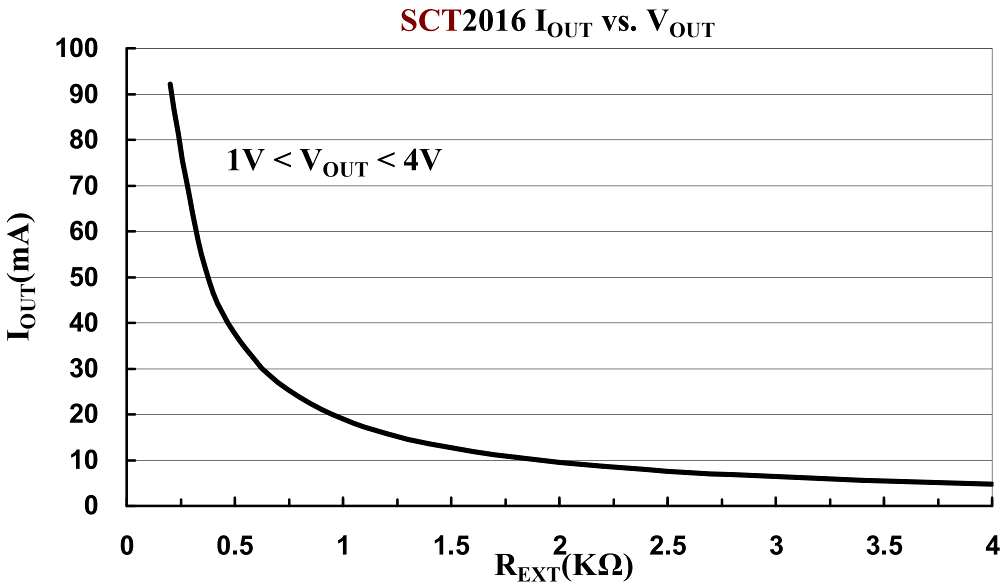


Timing Waveform



Adjusting Output Current

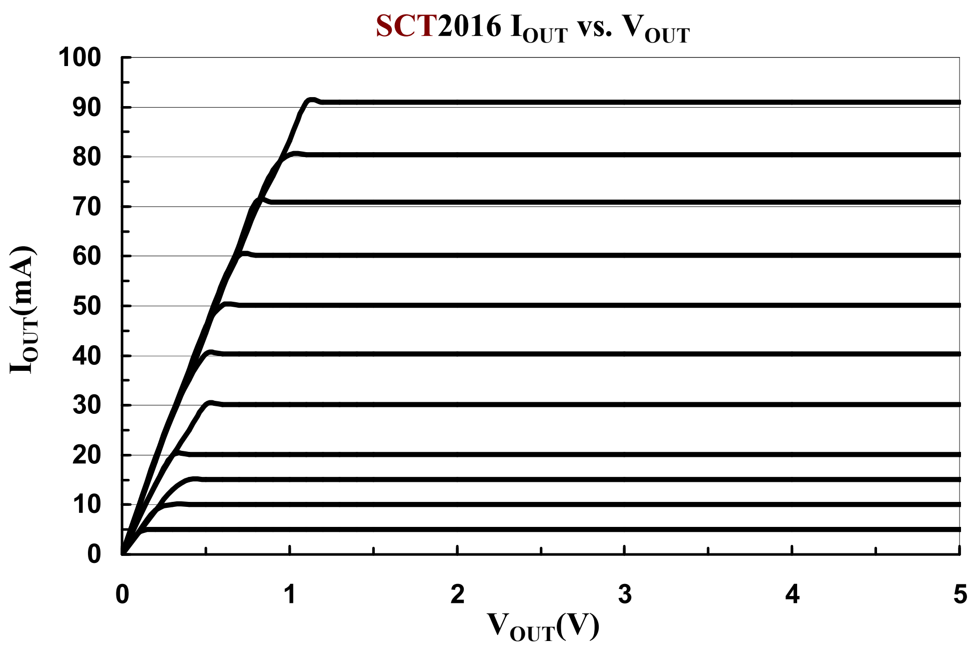
All SCT2016's output current (I_{OUT}) are set by one external resistor at pin REXT. The output current I_{OUT} versus resistance of R_{EXT} is shown as the following figure.



Furthermore, when SCT2016's output voltage is set between 1 Volt and 4 Volt, the output current can be estimated approximately by: $I_{OUT} = 30(630 / R_{EXT})$ (mA) (chip skew < ±6%). Thus the output current are to be set about 21mA at $R_{EXT} = 900\Omega$.

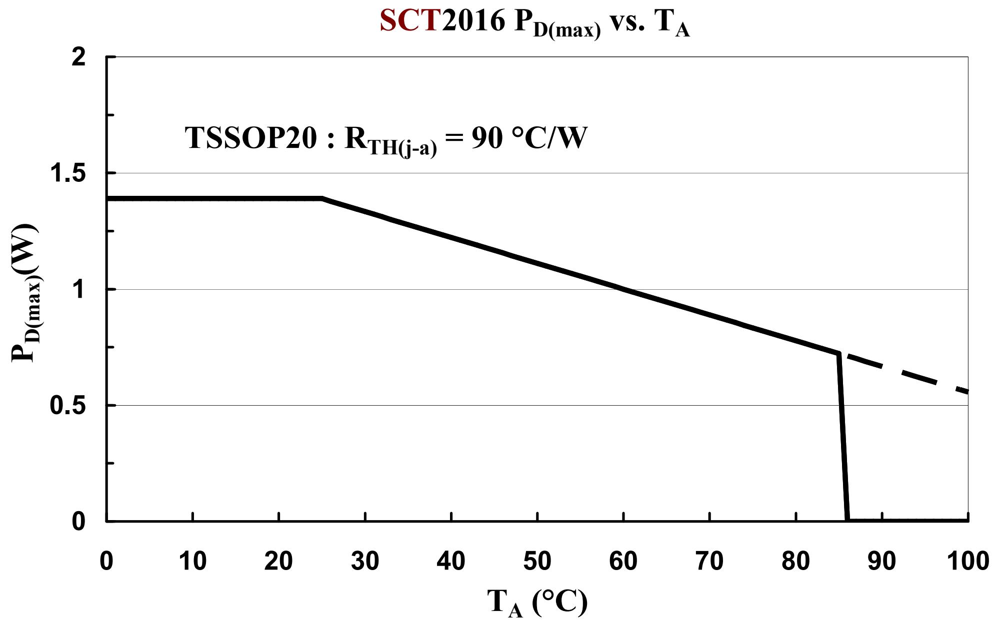
Output Characteristics

The current characteristic of output stage is flat. The output current remains constant regardless of the variations of LED forward voltage when $V_{OUT} > 1V$. The relationship between I_{OUT} and V_{OUT} is shown below:



Power Dissipation

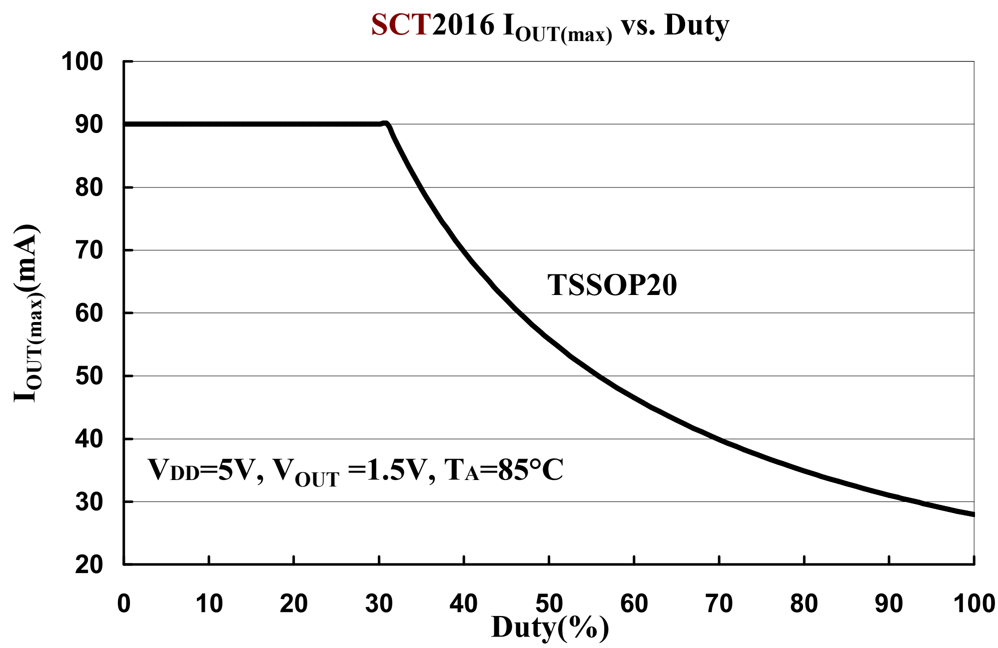
The power dissipation (P_D) of a semiconductor chip is limited by its package and ambient temperature. The maximum allowable power dissipation ($P_{D(max)}$) is determined as $P_{D(max)}=(T_{J(max)} - T_A)/R_{TH(j-a)}$ where $T_{J(max)}$: maximum chip junction temperature, usually considered as 150°C, T_A: ambient temperature, $R_{TH(j-a)}$: thermal resistance. Since P=IV, for sink larger I_{OUT}, users had better to add proper voltage reducers on output to reduce the heat generated from the SCT2016.



Limitation on Maximum Output Current

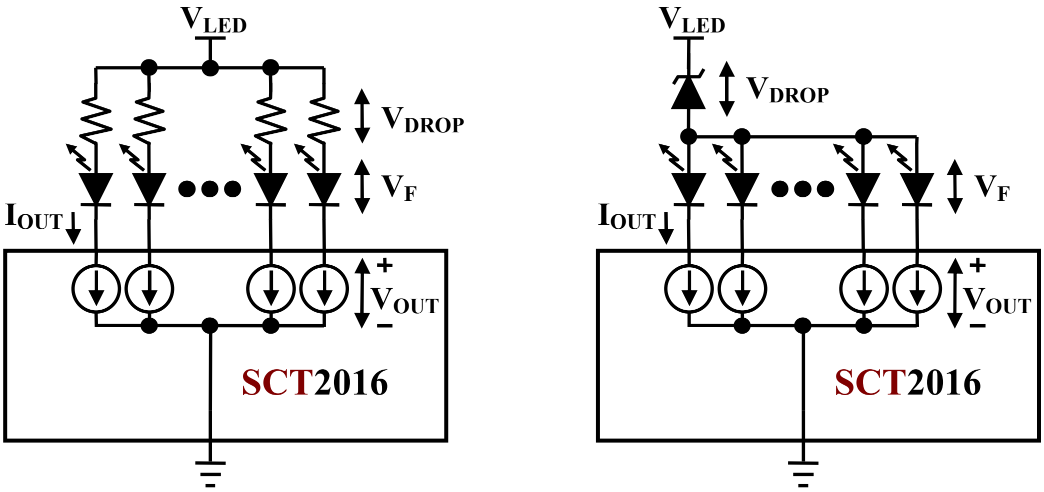
The maximum output current vs. duty cycle is estimated by:

$I_{OUT(max)}=(((T_{J(max)}-T_A)/R_{TH(j-a)})-(V_{DD}*I_{DD}))/V_{OUT}/Duty/N$, where $T_{J(max)}$=150°C, N=16(all ON)



Load Supply Voltage (V_{LED})

The SCT2016 can be operated very well when V_{OUT} ranging from 1V to 4V. It is recommended to use the lowest possible supply voltage or set a voltage reducer to reduce the V_{OUT} voltage, at the same time reduce the power dissipation of the SCT2016. Follow the diagram instructions shown below to lower down the output voltage. This can be done by adding additional resistor or zener diode, thus $V_{OUT}=V_{LED}-V_{DROP}-V_F$.

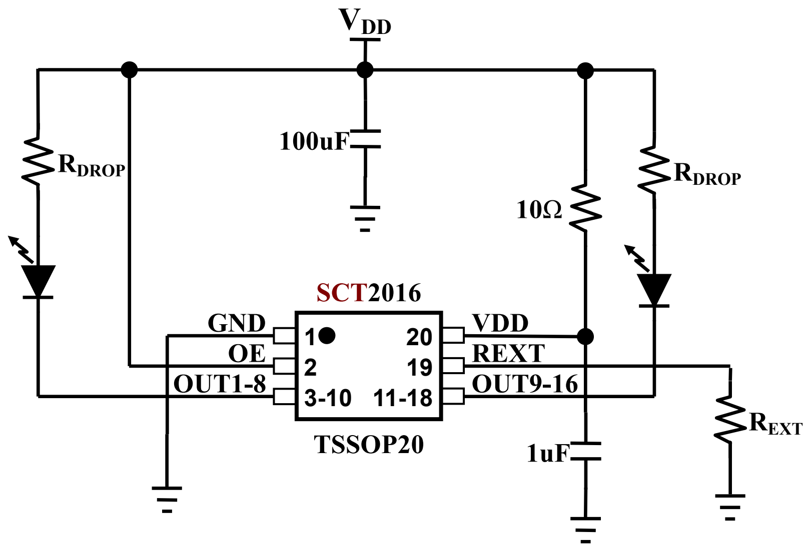


Over Temperature Shutdown

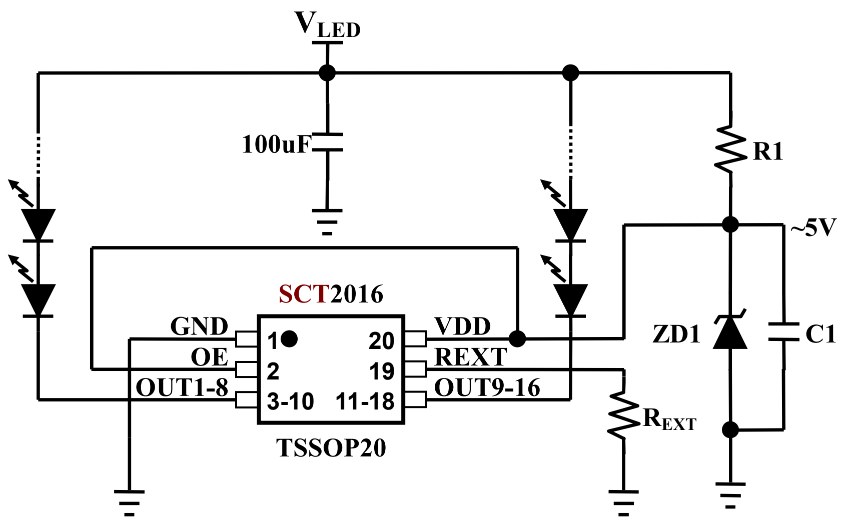
The SCT2016 contains thermal shutdown scheme to prevent damage from over heated. The internal thermal sensor turns off all outputs when the die temperature exceeds ~ +180°C. The outputs are enabled again when the die temperature drops below ~ +130°C.

Typical Application Circuits

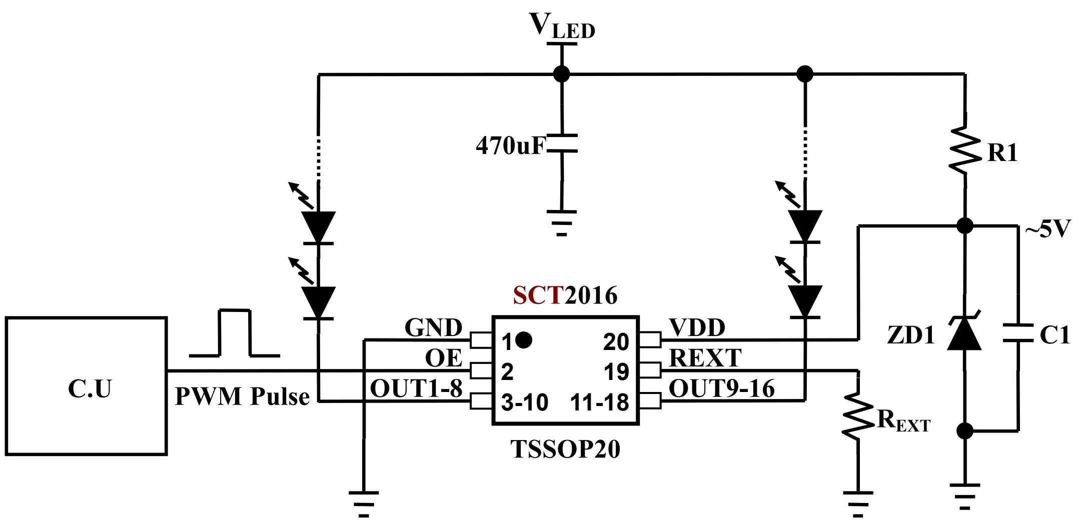
(1) Lighting with recommended V_{DD}=3.3/5V



(2) Lighting with V_{LED} > 5V, e.g. V_{LED}=12V/24V



(3) Lighting with dimming control

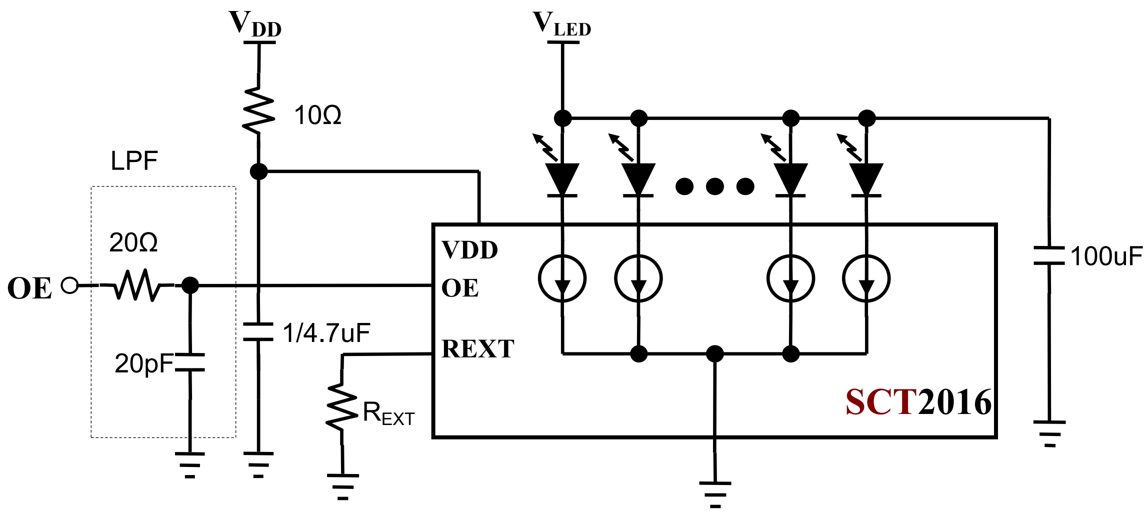


PCB Design Considerations

Use the following general guide-line when designing printed circuit boards (PCB):

Decoupling Capacitor

Place a decoupling capacitor e.g. 1uF between VDD and GND pins of SCT2016. Locate the capacitor as close to the SCT2016 as possible. This is normally adequate for static LED driving. For dynamic scan or PWM applications, it is necessary to add an additional capacitor of 4.7uF or more to each supply for every SCT2016. The necessary capacitance depends on the LED load current, PWM switching frequency, and serial-in data speed. Inadequate VDD decoupling can cause timing problems, and very noisy LED supplies can affect LED current regulation.



External Resistor (R_{EXT})

Locate the external resistor as close to the REXT pin as possible to avoid the noise influence.

Power and Ground

Maximizing the width and minimizing the length of VDD and GND trace improves efficiency and ground bouncing by effect of reducing both power and ground parasitic resistance and inductance. A small value of resistor e.g. 10Ω series in power input of the SCT2016 in conjunction with decoupling capacitor shunting the IC is recommended. Separating and feeding the LED power from another stable supply terminal V_{LED}, furthermore adding a larger capacitor e.g. 100uF beside the LED are strongly recommended.

EMI Reduction

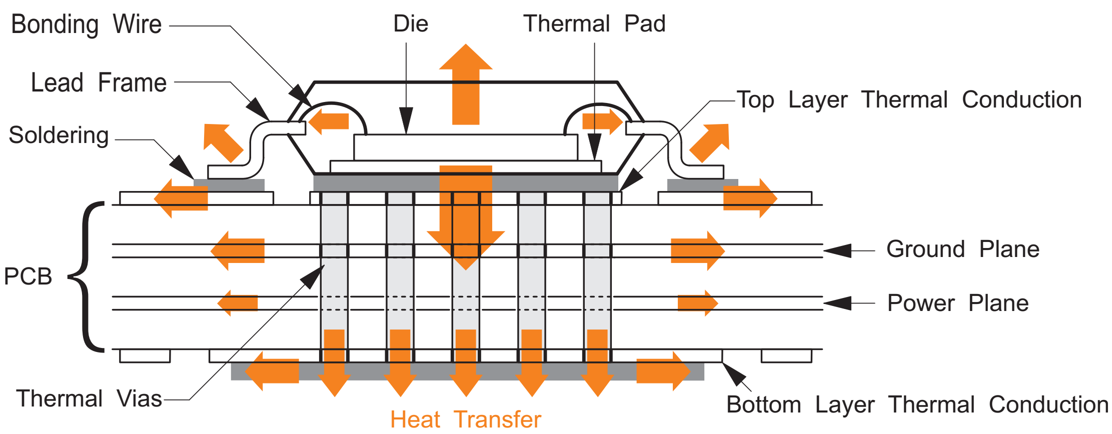
To reduce the EMI radiation from system, an economic solution RC low pass filter (LPF) is suggested to be used to lower the transient edge of clock input signal, as shown in the figure above. Using at least four layers PCB board with two interior power and ground planes is a good scheme to decrease the signal current path which is the source of radiation emission. As a result, EMI radiation can be decreased.

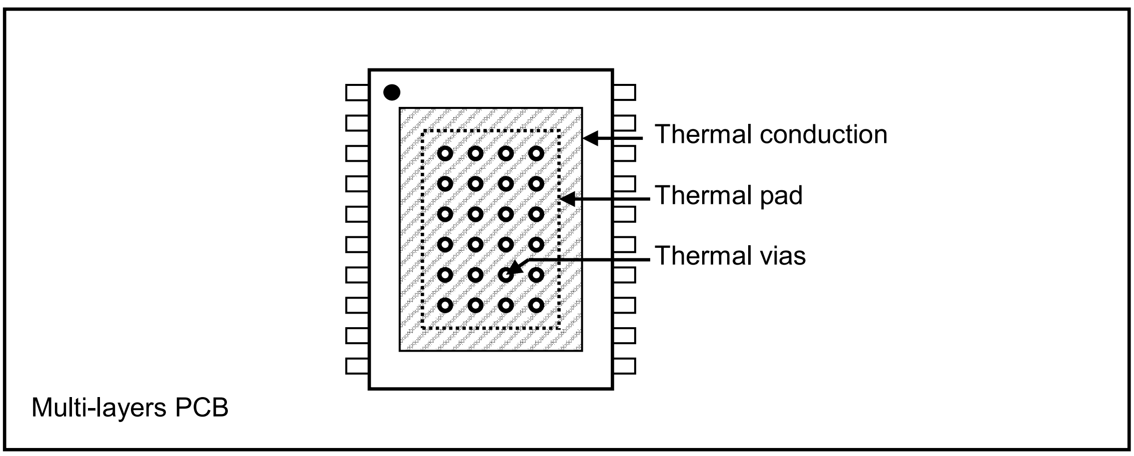
Thermal Pad Consideration

The “thermal pad” (also named “exposed pad”) TSSOP package beneath used to increase the heat dissipation capability is floating (NC), NOT wire-bonded to pin1 (ground terminal). User should be aware of this electrical connection when designing the PCB board, and make provisions for its use.

Usually, most of the heat generated from an IC is conducted to the PCB then radiates to the ambient. Thermal pad specifically increases the maximum power dissipation capability of the IC packages. To provide lower thermal resistance from the IC to the ambient air, PCB designers should layout larger thermal conduction areas on top layer (component side) and bottom layer (solder side) as well as thermal vias, the more the better. In addition, connecting thermal via to the ground plane also increases thermal conduction areas, this improves the heat transfer efficiency at the same time greatly dissipates heat generated from the package. Furthermore, coating solder on bottom layer and selecting e.g. 2 oz. copper which will increase the total thickness of thermal conduction is an alternative.

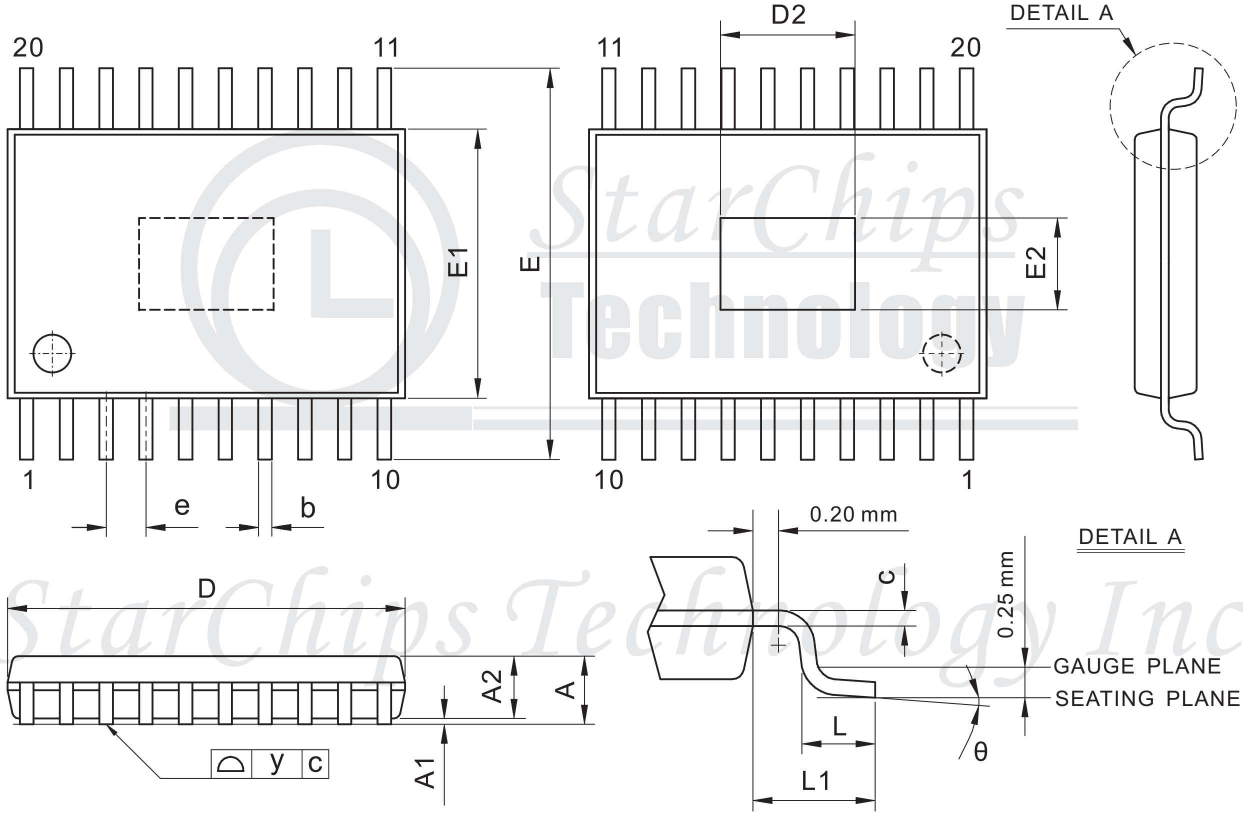
When making the solder paste screen, an opening should be created for the thermal pad. This way the thermal pad electrically and thermally connected to the PCB. As the thermal pad is soldered on copper polygon, the chance of inadvertently shorting the thermal pad to traces routed underneath it could be eliminated.





Package Dimension

TSSOP20TP(check up-to-date version)



Symbol	Dimension (mm)			Dimension (mil)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.20	-	-	47.2
A1	0.05	-	0.15	2.0	-	5.9
A2	0.80	0.90	1.05	31.5	35.4	41.3
b	0.19	-	0.30	7.5	-	11.8
c	0.09	-	0.20	3.5	-	7.9
D	6.40	6.50	6.60	252.0	255.9	259.8
E1	4.30	4.40	4.50	169.3	173.2	177.2
E	6.40 BSC			252.0 BSC		
e	0.65 BSC			25.6 BSC		
L1	1.00 REF			39.4 REF		
L	0.50	0.60	0.75	19.7	23.6	29.5
S	0.20	-	-	7.9	-	-
θ	0°	-	8°	0°	-	8°
D1	3.79	3.99	4.19	149.2	157.1	165.0
E2	2.60	2.80	3.00	102.4	110.2	118.1

Revision History (check up-to-date version)

Data Sheet Version	Remark
V02_02	Add thermal pad descriptions

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